

ABSTRACT OF THE DISCLOSURE

PACKAGING PLATFORM HAVING AN ADJUSTABLE THICKNESS

A platform (40) has a rigid body with an adjustable thickness (t) to selectively occupy any remaining space within a container (20) used for packaging items such as semiconductor wafers (22). The platform (40) in one example has a first portion (42) and a second portion (44). Adjusting the positions of the first and second portions (42, 44) relative to each other selectively varies the thickness (t) of the platform (40) to achieve the desired thickness.

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Figure 2